

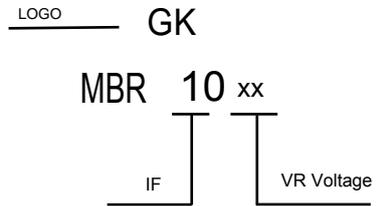
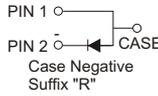
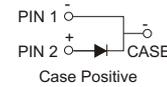
**VOLTAGE RANGE**  
20 to 200 Volts  
**CURRENT**  
10.0 Ampere

## FEATURES

- \* Low forward voltage drop
- \* High current capability
- \* High reliability
- \* High surge current capability
- \* Good for switching mode application

## MECHANICAL DATA

- \* Case: Molded plastic
- \* Epoxy: UL 94V-0 rate flame retardant
- \* Lead: Axial leads, solderable per MIL-STD-202, method 208 guaranteed
- \* Polarity: Color band denotes cathode end
- \* Mounting position: Any



## MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25°C ambient temperature unless otherwise specified.  
Single phase half wave, 60Hz, resistive or inductive load.  
For capacitive load, derate current by 20%.

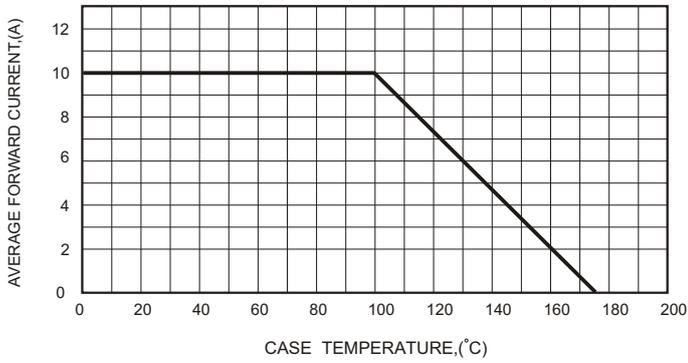
TYPE NUMBER	MBR1020	MBR1045	MBR1060	MBR1080	MBR10100	MBR10150	MBR10200	UNITS
Maximum Recurrent Peak Reverse Voltage	20	45	60	80	100	150	200	V
Maximum RMS Voltage	14	32	42	56	70	105	140	V
Maximum DC Blocking Voltage	20	45	60	80	100	150	200	V
Maximum Average Forward Rectified Current	10							A
Peak Forward Surge Current, 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)	150							A
Maximum Instantaneous Forward Voltage at 10A	0.55	0.7	0.85		0.92			V
Maximum DC Reverse Current Ta=25°C	0.1		0.02					mA
at Rated DC Blocking Voltage Ta=100°C	5		2					mA
Typical Junction Capacitance (Note1)	420							pF
Typical Thermal Resistance RθJC (Note 2)	2.5							°C/W
Operating Temperature Range Tj	-65 — +175							°C
Storage Temperature Range Tstg	-65 — +175							°C

### NOTES:

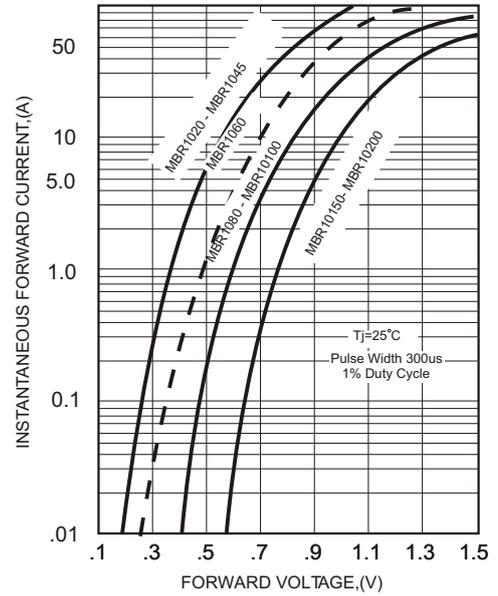
1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
2. Thermal Resistance Junction to Case.

**RATING AND CHARACTERISTIC CURVES**

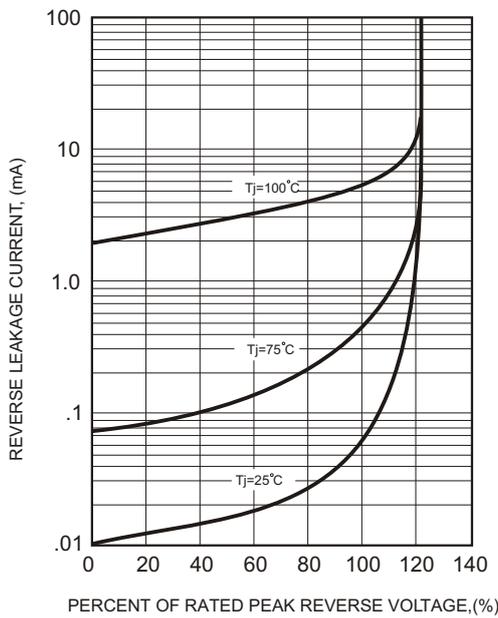
**FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE**



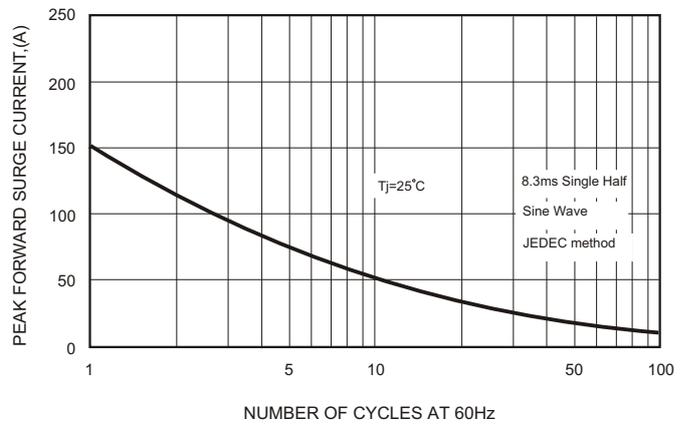
**FIG.2-TYPICAL FORWARD CHARACTERISTICS**



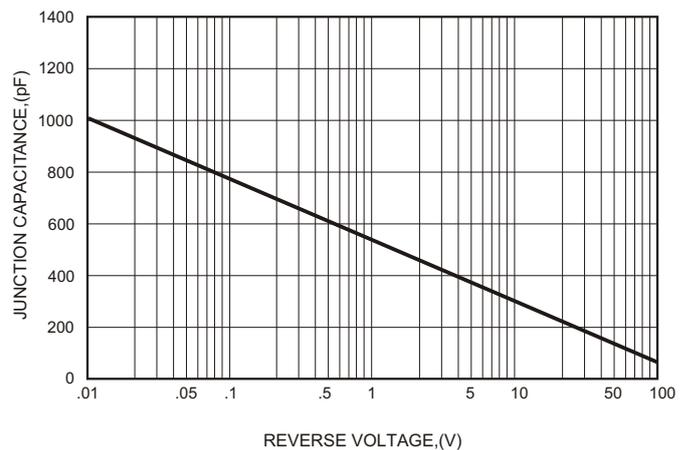
**FIG.3 - TYPICAL REVERSE CHARACTERISTICS**



**FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT**



**FIG.5-TYPICAL JUNCTION CAPACITANCE**



Soldering parameters

Reflow Condition		Pb-Free assembly (see as below)
Pre Heat	-Temperature Min ( $T_{s(min)}$ )	+150 °C
	-Temperature Max( $T_{s(max)}$ )	+200 °C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp ( $T_L$ ) to peak)		3 °C/sec. Max
$T_{s(max)}$ to $T_L$ - Ramp-up Rate		3 °C/sec. Max
Reflow	-Temperature( $T_L$ )(Liquid us)	+217 °C
	-Temperature( $t_L$ )	60-150 secs.
Peak Temp ( $T_P$ )		+260(+0/-5) °C
Time within 5 °C of actual Peak Temp ( $t_p$ )		30 secs. Max
Ramp-down Rate		6 °C/sec. Max
Time 25 °C to Peak Temp ( $T_P$ )		8 min. Max
Do not exceed		+260 °C



Package Dimensions & Suggested Pad Layout

